

ABSTRACT OF THE DISCLOSURE

A packaged integrated circuit which includes a die 700 having a surface and corners separated by edges. The die surface includes depressions 600, 720 so
5 that mold compound 114 covering the die surface fills the depressions. The filling of the depressions in the die surface enhances the adhesion of the mold compound to the die. The die can include bond pads 714, in which case the depressions can take the form of slots 720 in the bond pads. In addition, the depressions can take the form of trenches 600 at the surface of the die in a
10 dielectric layer 703. The trenches can be at the die corners and along the die edges.